

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	6039	(interconnect\$5 with (trench via opening hole recess groove damascene dual adj damascene)) with (copper 'cu')	US-PGPU B; USPAT; EPO; JPO	OR	ON	2005/12/15 07:39
L2	6895	(interconnect\$5 with (trench via opening hole recess groove damascene dual adj damascene)) with (copper 'cu')	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 07:39
L3	6895	2 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu')	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 07:40
L4	677	3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with nitrogen	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 07:41
L5	868	3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with water	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/15 07:41

L7	31	3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with (water with nitrogen)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/12/15 07:42
L8	3926	3 and (interconnect\$5 trench via opening hole recess groove damascene dual adj damascene copper 'cu') with (barrier diffusion) near4 (layer film)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/12/15 07:43
L9	2919	3 and (copper 'cu') near4 (barrier diffusion) near4 (layer film)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/12/15 07:44
L10	785	9 and (copper 'cu' barrier diffusion layer film) with nitrogen	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/12/15 07:45
L11	28	9 and (copper 'cu' barrier diffusion layer film) with (nitrogen with water)	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2005/12/15 07:45